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General Information

Series	CBR-SMD RF COG
Style	SMD Chip
Description	SMD, Fixed, RF, Ultra High Q, Low ESR, Class I
Features	Ultra High Q, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	12.03 mg
Notes	Solder Wave or Solder Reflow.
Shelf Life	78 Weeks
MSL	1

Dimensions

Chip Size	0805
L	2mm ± 0.2 mm
W	1.25mm ± 0.2 mm
T	0.85mm ± 0.1 mm
B	0.5mm ± 0.2 mm

Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	4000

Specifications

Capacitance	9.9 pF
Tolerance	± 0.5 pF
Voltage DC	500 VDC
Dielectric Withstanding Voltage	750 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Dissipation Factor	0.167%
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	10 GOhms
Quality Factor	598

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